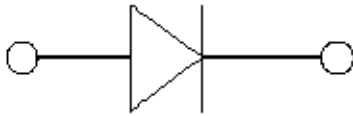


# BAS321

## Small-Signal Switching Diodes



### Features

- VR 200V
- I<sub>FAV</sub> 200mA

### Typical Applications

- Extreme fast switches

### Mechanical Data

- **Package:** SOD323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end
- **Marking:** T3

### ■ Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Repetitive peak reverse voltage	V <sub>RRM</sub>	V		250
Reverse Voltage	V <sub>R</sub>	V		200
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	A	t=8.3ms, Half sine-wave	2
Average forward current	I <sub>FAV</sub>	mA		200
Power dissipation	P <sub>D</sub>	mW		250
Junction temperature	T <sub>j</sub>	°C		150
Storage temperature range	T <sub>stg</sub>	°C		-55 to +150

### ■ Electrical Characteristics (Ta=25°C Unless otherwise specified)

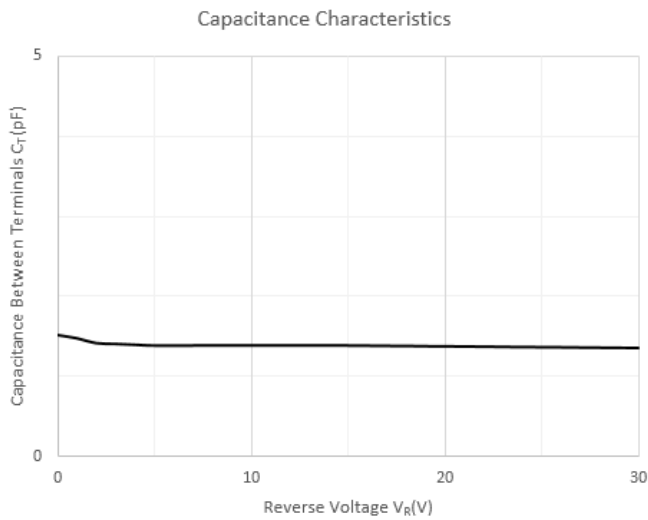
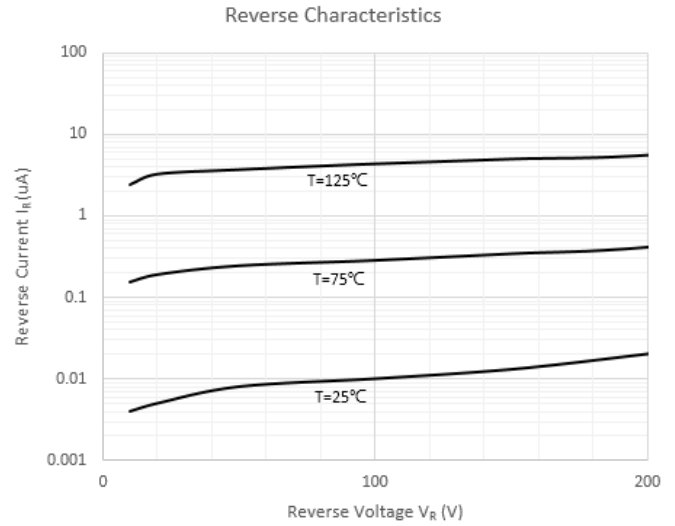
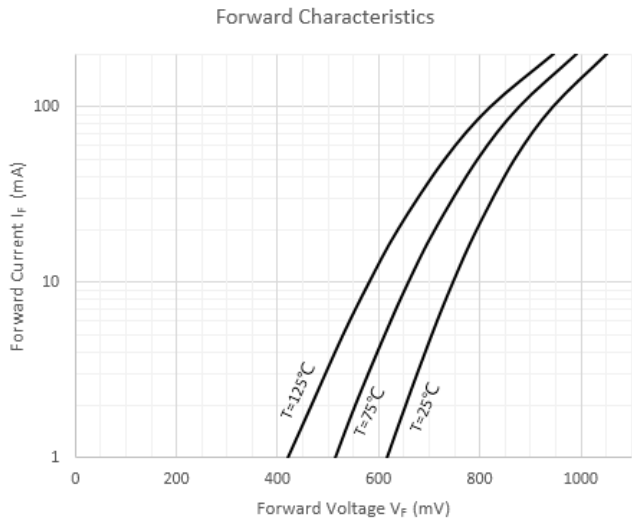
PARAMETER	SYMBOL	UNIT	Conditions	Min	Max
Maximum Forward voltage	V <sub>F</sub>	V	I <sub>F</sub> =100mA		1.0
			I <sub>F</sub> =200mA		1.25
Maximum Reverse current	I <sub>R</sub>	nA	V <sub>R</sub> =200V		100
Minimum Breakdown voltage	V <sub>R</sub>	V	I <sub>R</sub> =10uA	200	
Maximum Diode capacitance	C <sub>D</sub>	pF	V <sub>R</sub> =0V, f =1MHz		5
Maximum Reverse recovery time	t <sub>rr</sub>	ns	I <sub>F</sub> =I <sub>R</sub> =30 mA,RL=100Ω,IRR=3mA		50

# BAS321

## Ordering Information (Example)

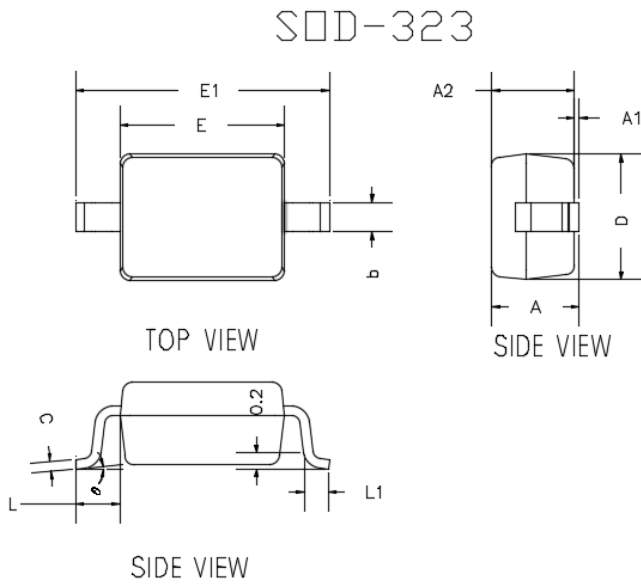
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BAS321	F2	Approximate 0.0048	3000	30000	120000	7" reel

## Characteristics(Typical)



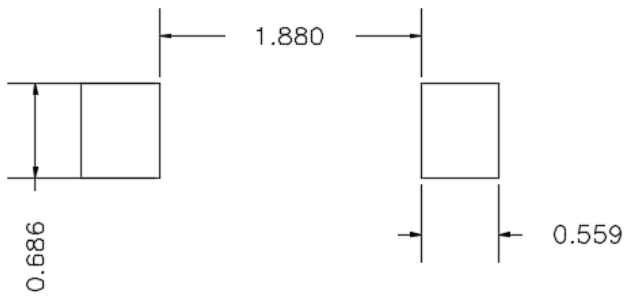
# BAS321

## ■Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
e	0°	8°	0°	8°

## ■Soldering Footprint



UNIT : mm

SUGGESTED SOLDER PAD LAYOUT

## BAS321

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### Disclaimer

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